

IPC MARKET RESEARCH

PCB Technology Trends 2016



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Strengthening & Advancing Electronics Manufacturing Globally



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Sections 1 through 6 cover the following topics*:

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| <p>1) Demographics
 Geographic Representation
 Industry Segments
 Product Types
 Market Segments
 PCB Expansion Plans</p> | <p>4) Materials
 Rigid Materials
 Flexible and Stretchable Materials
 Metal Core
 Reinforcement Materials
 Thermal Properties
 Loss Characteristics
 Lead-Free
 Halogen-Free
 Surface Finishes
 Lamination Cycles</p> |
| <p>2) Board Properties
 Board Thickness and High-Density
 Interconnect
 Layer Count
 Heat Dissipation
 Through-Hole Boards Designed for
 Assembly with Press-Fit Technology</p> | <p>5) Special Structures
 Embedded Components
 Optical Channels
 Chip Packages or Modules</p> |
| <p>3) Miniaturization
 Line Width and Spacing
 I/O Pitch
 Linear Dimensions
 Density
 Via Diameters
 Aspect Ratios
 Via Structure
 Via Filling</p> | <p>6) Printed Electronics
 PE Usage and Types
 Printing Processes
 PE Applications
 3D Printing</p> |
| | <p>7) Issues and Trends
 Traceability
 Recyclable Content
 Compliance Challenges
 Biggest Technical Challenges
 Trends</p> |

*Not all topics are included in every section. In cases where insufficient valid survey responses were collected, the data are omitted.